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Part Number:

0738001000

Status:

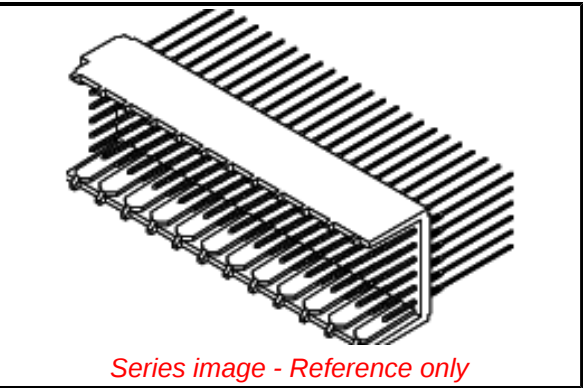
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End Option, 144 Circuits



Series image - Reference only

Documents:

- [3D Model](#)
- [3D Model \(PDF\)](#)
- [Drawing \(PDF\)](#)
- [Product Specification PS-73780-999-001 \(PDF\)](#)
- [Packaging Specification PK-70873-0868 \(PDF\)](#)
- [Test Summary TS-73670-990-001 \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73800

Application

Midplane

Component Type

PCB Header

Overview

HDM Backplane Connector System

Product Name

HDM

UPC

800755946376

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Plating Mating

Gold

Material - Plating Termination

Gold

Material - Resin

High Temperature Thermoplastic

Net Weight

8.289/g

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

11.50mm

PCB Locator

No

PCB Retention

Yes

PCB Thickness - Recommended

4.00mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

0.051µm

Polarized to PCB

No

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55° to +105°C

Electrical

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73800 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard
Receptacle. 73780 HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.

Global

Description

Product #

Backplane Insertion

622005703

Head for 144 Circuits

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Lead-freeProcess Capability	N/A
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0868
Product Specification	PS-73780-999-001
Sales Drawing	SD-73800-001
Test Summary	TS-73670-990-001

This document was generated on 12/12/2019

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